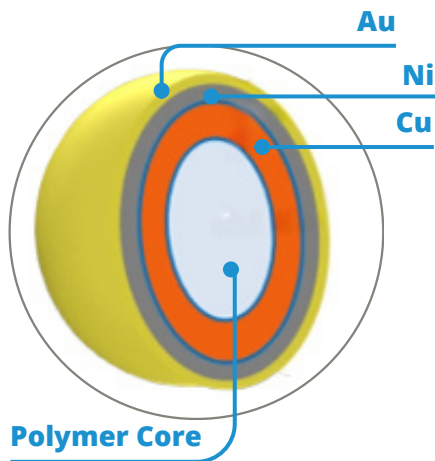


# DATA SHEET POLYMER CORE SOLDER BALLS

## General informations



- Alternative to traditional non-collapsible lead solder balls
- Minimize mechanical stress
- Improve reliability and reparability
- Compatible with solder reflow according to IPC-J-STD-001
- Miniaturisation
- Flexible design w/ different possible coating
- Excellent corrosion resistance with extended shelf life (up to 1 year)
- Can be mounted using ICA or solder paste (lead free compatible)
- Controlled stand-off height (+/-5%)

Polymer core solder balls help improving the lifespan of electrical contact for assembling BGAs on a printed circuit board

## Technical Data

Reference	PCSB_280_Au
Ball size	280 $\mu\text{m}$ +/- 5%
Coating design* : from 50 nm to 20 $\mu\text{m}$	Cu Ni Au
Ball weight	~ 0.045g / 1000 balls

